Special Issue

Advances in Thermal and Fluid Process Characterization

Message from the Guest Editor

Today's scientific and engineering processes require precise and reliable thermal and fluid characterization. This may involve experimental diagnostics, computational simulations or theoretical treatments. The topic is broad, and we invite contributions regarding a wide range of thermal and fluid phenomena. Examples include, but are not limited to: climate, industrial processes, heat transfer, complex geometry, multi-phase flows, environmental monitoring, and fluid control. Innovative methods and results that monitor and analyze these processes are of interest. Thermal and fluid phenomena are ubiquitous in nature and engineering devices/systems, and in most instances the interactions between the flow and temperature fields lead to new complexities. Thus, advances in their characterization are promoted and promulgated through this Special Issue.

Guest Editor

Dr. T.-W. Lee

Mechanical and Aerospace Engineering, SEMTE, Arizona State University, Tempe, AZ 85287, USA

Deadline for manuscript submissions

closed (20 June 2023)

Applied Sciences

an Open Access Journal by MDPI

Impact Factor 2.5
CiteScore 5.5

mdpi.com/si/125255

Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
applsci@mdpi.com

mdpi.com/journal/applsci

Applied Sciences

an Open Access Journal by MDPI

Impact Factor 2.5
CiteScore 5.5

mdpi.com/journal/applsci

MDPI

About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, CAPlus / SciFinder, and other databases.

Journal Rank:

JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)